

Centerline Technologies uses computerized diamond saws and CNC controlled surface grinders capable of scribing or dicing a variety of shaped parts up to .200" thick in geometries. Centerline also will offer diamond machined edges, bevels, V grooves and chamfers per your specifications.

Benefits of dicing substrates are:

- Superior edge quality
- Optical alignment
- Tighter tolerances (accuracy +/- .0003' repeatability within .0001")
- No heat effected zone
- No stress
- Cleaner environment
- Smaller cell sizes (.005" x .005")
- Fully patterned substrates (subdivide with computer programmed auto recognition software)
- Thicknesses range from .003" - .200" thick

Centerline Technologies will recommend the proper method of mounting you parts for processing depending on the part size, material thickness and required tolerances. This could be PVC, UV tape or mounted on glass. It is strongly recommended that you contact your vendor of choice before layout of circuits to help provide the most economical and highest quality end product.

Centerline Technologies takes great pride in producing a superior product consistently and repeatedly. Please review our capabilities and polishing and lapping information. Talk to us. Ask questions. Find out why Centerline Technologies should be your preferred source for high quality polished and lapped substrate materials.

Centerline Technologies

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